

COATED COPPER WIRE FOR BONDING APPLICATIONSAbstract

5

The invention is related to a bonding wire, comprising a core with a surface, wherein the core comprises copper as a main component, and a coating layer superimposed over the surface of the core, wherein the

10 core comprises copper as a main component, and a coating layer superimposed over the surface of the core, wherein the coating layer comprises palladium as a main component, wherein the core comprises at least 5 ppm silver and at least 20 ppm phosphorus as further components,

15 wherein the wire meets the relation $0.0008 < E/(d \cdot CP) < 0.0375$, wherein E is an elongation of the wire measured in %, d is a diameter of the wire measured in μm and CP is the phosphorus content of the wire core measured in ppm.

20

Fig. 1